

**Average Weight: 0.232g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die (FPGA)</b>					<b>0.009340</b>	<b>4.025</b>
	Silicon (Si)	7440-21-3	99.70	Silicon IC	0.009310	
	Aluminium(Al)	7429-90-5	0.20	Silicon IC	0.000020	
	Copper (Cu)	7440-50-8	0.05	Silicon IC	0.000005	
	Tantalum (Ta)	7440-25-7	0.05	Silicon IC	0.000005	
<b>Die Attach</b>					<b>0.001703</b>	<b>0.734</b>
	Silver (Ag)	7440-22-4	75.00	Glue	0.001280	
	Epoxy Cresol Novolak	29690-82-2	24.80	Glue	0.000420	
	Diisobutyrate derivate	6846-50-0	0.20	Glue	0.000003	
<b>Bonding Wire</b>					<b>0.000530</b>	<b>0.228</b>
	Gold (Au)	7440-57-5	100.00	Wire	0.000530	
<b>Molding Compound</b>					<b>0.147860</b>	<b>63.736</b>
	Biphenyl epoxy resin	85954-11-6	12.00	Encapsulation	0.017740	
	Phenol resin	9003-35-4	7.00	Encapsulation	0.010350	
	Quartz	14808-60-7	2.50	Encapsulation	0.003700	
	Silica, vitreous	60676-86-0	77.00	Encapsulation	0.113850	
	Carbon black	1333-86-4	0.50	Encapsulation	0.000740	
	Antimony Trioxide	1309-64-4	0.50	Encapsulation	0.000740	
Brominated epoxy resin (Halogen)	68541-56-0	0.50	Encapsulation	0.000740		
<b>Solder Balls</b>					<b>0.016585</b>	<b>7.149</b>
	Tin (Sn)	7440-31-5	98.27	Base metal	0.016300	
	Silver (Ag)	7440-22-4	1.20	Base metal	0.000200	
	Copper (Cu)	7440-50-8	0.50	Base metal	0.000080	
	Nickel (Ni)	7440-02-0	0.02	Base metal	0.000003	
	Lead (Pb)	7439-92-1	0.01	Impurity	0.000002	

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<b>Substrate</b>						
<b>Core &amp; Fiber Glass</b>					<b>0.031930</b>	<b>13.763</b>
	Fiberglass	65997-17-3	43.00	Substrate	0.013730	
	Epoxy Cresol Novolak	29690-82-2	10.00	Substrate	0.003190	
	Bisphenol epoxy resin	25068-38-6	10.00	Substrate	0.003190	
	Brominated compound (Halogen)	68541-56-0	7.00	Substrate	0.002240	
	Bismaleimide (B)	13676-54-5	14.50	Substrate	0.004630	
	Triazine (T)	25722-66-1	14.50	Substrate	0.004630	
	Magnesium silicate	13776-74-4	0.50	Substrate	0.000160	
	Amorphous Silica	7631-86-9	0.50	Substrate	0.000160	
<b>Solder Mask</b>					<b>0.005210</b>	<b>2.246</b>
	Barium sulfate	7727-43-7	20.00	Substrate	0.001040	
	Epoxy Resin	85954-11-6	35.00	Substrate	0.001830	
	Talc containing no asbestiform fibers	14807-96-6	3.15	Substrate	0.000160	
	Silica crystalline	14808-60-7	0.45	Substrate	0.000020	
	Acrylic Resin	68586-16-6	40.00	Substrate	0.002090	
	Ammine compound	Trade secret	1.40	Substrate	0.000070	
<b>Coating</b>					<b>0.018830</b>	<b>8.117</b>
	Copper (Cu)	7440-50-8	98.50	Substrate	0.018590	
	Nickel (Ni)	7440-02-0	1.00	Substrate	0.000150	
	Gold (Au)	7440-57-5	0.50	Substrate	0.000090	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/06/08	1.0	Initial Xilinx release.
7/29/11	1.1	100% Material Declaration

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